



BSI Standards Publication

## Electronic components – Long-term storage of electronic semiconductor devices

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Part 4: Storage (IEC 62435-4:2018)

## National foreword

This British Standard is the UK implementation of EN IEC 62435-4:2018. It is identical to IEC 62435-4:2018.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its secretary.

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English Version

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Composants électroniques - Stockage de longue durée des  
dispositifs électroniques à semiconducteurs - Part 4:  
Stockage  
(IEC 62435-4:2018)

Elektronische Bauteile - Langzeitlagerung elektronischer  
Halbleiterbauelemente - Teil 4: Lagerung  
(IEC 62435-4:2018)

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European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

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## **European foreword**

The text of document 47/2469/FDIS, future edition 1 of IEC 62435-4, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62435-4:2018.

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- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2021-07-10

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In the official version, for Bibliography, the following notes have to be added for the standards indicated:

|                  |                                     |
|------------------|-------------------------------------|
| IEC 60068-2-17   | NOTE Harmonized as EN 60068-2-17    |
| IEC 60721-3-1    | NOTE Harmonized as EN IEC 60721-3-1 |
| IEC 60749-30     | NOTE Harmonized as EN 60749-30      |
| IEC 61340-5-1    | NOTE Harmonized as EN 61340-5-1     |
| IEC 61340-5-3    | NOTE Harmonized as EN 61340-5-3     |
| IEC 61760-2      | NOTE Harmonized as EN 61760-2       |
| IEC 62258 series | NOTE Harmonized as EN 62258 series  |
| IEC 62435 series | NOTE Harmonized as EN 62435 series  |
| IEC 62435-2      | NOTE Harmonized as EN 62435-2       |

## Annex ZA

(normative)

### Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: [www.cenelec.eu](http://www.cenelec.eu).

| <u>Publication</u> | <u>Year</u> | <u>Title</u>                                                                                                                                                                                                 | <u>EN/HD</u>     | <u>Year</u> |
|--------------------|-------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------|-------------|
| IEC 60749-20-1     | -           | Semiconductor devices - Mechanical and climatic test methods - Part 20-1: Handling, packing, labelling and shipping of surface-mount devices sensitive to the combined effect of moisture and soldering heat | EN 60749-20-1    | -           |
| IEC/TR 61340-5-2   | -           | Electrostatics -- Part 5-2: Protection of electronic devices from electrostatic phenomena - User guide                                                                                                       | CLC/TR 61340-5-2 | -           |
| IEC/TR 62258-3     | -           | Semiconductor die products -- Part 3:- Recommendations for good practice in handling, packing and storage                                                                                                    |                  | -           |
| JEDEC J-STD-033    | -           | Standard for handling, packing, shipping, and use of moisture/reflow sensitive surface mount devices                                                                                                         |                  |             |
| MIL-PRF-27401      | -           | Propellant pressurizing agent nitrogen                                                                                                                                                                       |                  |             |
| MIL-PRF-81705      | -           | ESD Materials, Bags and Performance Specification                                                                                                                                                            |                  |             |

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